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EMIF08-2005QEJ

IPAD™

EMI FILTER INCLUDING ESD PROTECTION

APPLICATIONS:

Where EMI filtering in ESD sensitive equipment is required:

- Computers and printer
- Communication systems
- Mobile phones

DESCRIPTION

The EMIF08-2005QEJ is a highly integrated device designed to suppress EMI/RFI noise in all systems subjected to electromagnetic interferences. Additionally, the EMIF08-2005QEJ filter includes an ESD protection circuitry which prevents destruction when subjected to ESD discharge up to 15kV.

BENEFITS

- EMI symmetrical low-pass filter
- Low PCB space consuming: 9 mm²
- Very thin package < 1 mm
- High reliability offered by monolithic integration

${\color{blue} \textbf{COMPLIES WITH THE FOLLOWING STANDARDS:} }$

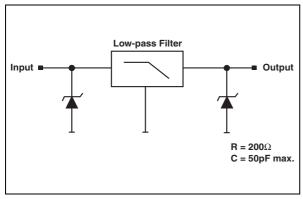
IEC61000-4-2:

15kV (air discharge)8kV (contact discharge)

MIL STD 883E - Method 3015-7 Class 3:

25kV (human body test)

Figure 3: Basic Cell Configuration



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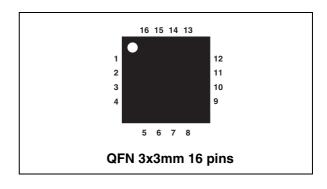
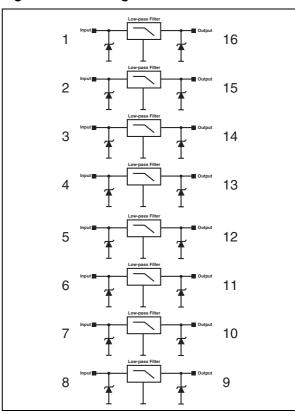


Table 1: Order Code

Part Number	Marking
EMIF08-2005QEJ	EM08

Figure 2: Pin Configuration



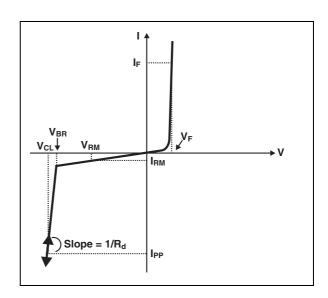
EMIF08-2005QEJ

Table 2: Absolute Ratings (Tamb = 25° C)

Symbol	Paramete	Value	Unit	
V _{PP}	ESD discharge EC61000-4-2 air discharge IEC61000-4-2 contact discharge		± 15 ± 8	kV
T _j	Junction temperature	125	°C	
T _{stg}	Storage temperature rang	- 55 +150	°C	
T _L	Maximum lead temperatu	260	°C	

Table 3: Electrical Characteristics (T_{amb} = 25 $^{\circ}C$)

Symbol	Parameter			
V_{BR}	Breakdown voltage			
I _{RM}	Leakage current @ V _{RM}			
V_{RM}	Stand-off voltage			
V_{CL}	Clamping voltage			
I _{PP}	Peak pulse current			
αΤ	Voltage temperature coefficient			
V _F	Forward voltage drop			
R _{I/O} Series resistance between Input & Output				
C _{line}	Input capacitance per line			



Symbol	Test conditions		Тур.	Max.	Unit
V _{BR}	I _R = 1 mA		8	10	V
I _{RM}	V _{RM} = 3V per line			500	nA
R _d	$I_{PP} = 10A, t_p = 2.5 \mu s$		1		Ω
R _{I/O}		180	200	220	Ω
C _{in}	$V_{\text{bias}} = 0V$ F = 1MHz $V_{\text{osc}} = 30\text{mV}$		45	50	pF

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Figure 3: Filtering behavior

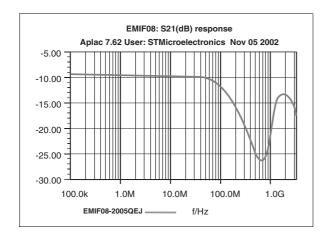


Figure 4: Capacitance versus reverse applied voltage

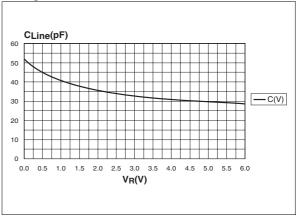
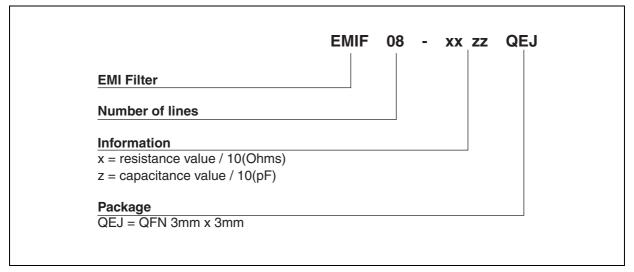
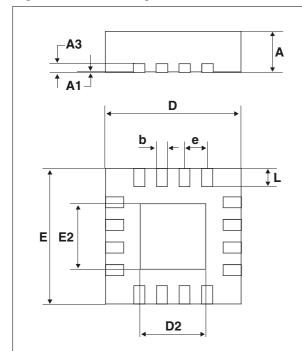


Figure 5: Ordering Information Scheme



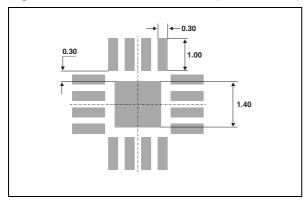
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Figure 6: QFN Package Mechanical Data



	DIMENSIONS						
REF.	Millimeters		ers	Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	0.80		1.00	0.031		0.039	
A1	0		0.05	0		0.002	
А3		0.20			0.008		
b	0.18		0.30	0.007		0.012	
D		3.00			0.118		
D2	1.25		1.55	0.049		0.061	
Е		3.00			0.118		
E2	1.25		1.55	0.049		0.061	
е		0.50			0.020		
K	0.20			0.008			
L	0.30	0.40	0.50	0.012	0.016	0.020	

Figure 7: Foot Print Dimensions (in millimeters)



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Table 4: Ordering Information

Ordering code	Marking	Package	Weight	Base qty	Delivery mode
EMIF08-2005QEJ	EM08	QFN 3x3 16 pins	22.1 mg	3000	Tape & reel

Table 5: Revision History

Date	Revision	Description of Changes
Dec-2002	2A	Last issue.
03-Jan-2005	3	Minor template update. No content change.
01-Apr-2005	4	QFN package mechanical data update: 1/ References A typ., A1 typ., b typ. D2 typ. and E2 typ. removed. 2/ Reference D2 changed from 0.25 min. to 1.25 min. and from 1.25 max. to 1.55 max. 3/ Reference E2 changed from 0.25 min. to 1.25 min. and from 1.25 max. to 1.55 max. 4/ Footprint updated, in compliance with IPC-SM-782.

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